

Title (en)

SINTERED BODY OF TiAl INTERMETALLIC COMPOUND AND METHOD FOR PRODUCING SINTERED BODY OF TiAl INTERMETALLIC COMPOUND

Title (de)

SINTERKÖRPER AUS EINER INTERMETALLISCHEN TIAL-VERBINDUNG UND VERFAHREN ZUR HERSTELLUNG EINES SINTERKÖRPERS AUS EINER INTERMETALLISCHEN TIAL-VERBINDUNG

Title (fr)

CORPS FRITTÉ DE COMPOSÉ INTERMÉTALLIQUE TiAl, ET PROCÉDÉ DE PRODUCTION DE CORPS FRITTÉ DE COMPOSÉ INTERMÉTALLIQUE TiAl

Publication

EP 3415648 A1 20181219 (EN)

Application

EP 17778878 A 20170221

Priority

- JP 2016075932 A 20160405
- JP 2017006390 W 20170221

Abstract (en)

The sintered density of a TiAl-based intermetallic sintered compact is improved. A method for producing a TiAl-based intermetallic sintered compact includes sintering TiAl-based powder to produce the TiAl-based intermetallic sintered compact, the TiAl-based powder containing a TiAl-based intermetallic compound in which Ti and Al are bonded and an additional metal. The additional metal is Ni, or Ni and Fe.

IPC 8 full level

C22C 1/04 (2006.01); **B22F 1/10** (2022.01); **B22F 3/02** (2006.01); **B22F 3/10** (2006.01); **C22C 1/00** (2006.01); **C22C 14/00** (2006.01); **C22C 21/00** (2006.01)

CPC (source: EP US)

B22F 1/10 (2022.01 - EP US); **B22F 3/16** (2013.01 - US); **B22F 3/225** (2013.01 - EP US); **C22C 1/00** (2013.01 - EP US); **C22C 1/0416** (2013.01 - EP US); **C22C 1/0458** (2013.01 - EP US); **C22C 1/047** (2023.01 - EP US); **C22C 14/00** (2013.01 - EP US); **C22C 21/00** (2013.01 - EP US); **B22F 2301/052** (2013.01 - US); **B22F 2301/205** (2013.01 - US); **B22F 2301/40** (2013.01 - US); **B22F 2304/10** (2013.01 - US); **B22F 2998/10** (2013.01 - US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

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